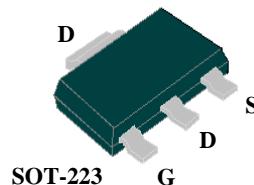




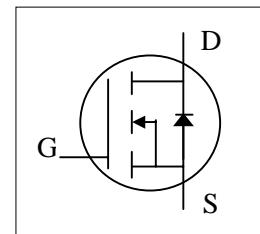
- ▼ Simple Drive Requirement
- ▼ Lower Gate Charge
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	60V
$R_{DS(ON)}$	90mΩ
I_D	4.1A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.



Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}^3$	4.1	A
$I_D @ T_A = 70^\circ\text{C}$	Drain Current, $V_{GS} @ 10\text{V}^3$	3.3	A
I_{DM}	Pulsed Drain Current ¹	20	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation	2.8	W
	Linear Derating Factor	0.02	W/ $^\circ\text{C}$
E_{AS}	Single Pulse Avalanche Energy ⁴	1.8	mJ
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	45	$^\circ\text{C}/\text{W}$



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to 25°C , $I_{\text{D}}=1\text{mA}$	-	0.057	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=4\text{A}$	-	-	90	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=2\text{A}$	-	-	110	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.8	-	2.5	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=4\text{A}$	-	4	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
	Drain-Source Leakage Current ($T_j=70^\circ\text{C}$)	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$	-	-	25	μA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge	$I_{\text{D}}=4\text{A}$	-	6.5	10.5	nC
Q_{gs}	Gate-Source Charge	$V_{\text{DS}}=48\text{V}$	-	1.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=4.5\text{V}$	-	3.5	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time ²	$V_{\text{DS}}=30\text{V}$	-	5	-	ns
t_r	Rise Time	$I_{\text{D}}=1\text{A}$	-	6	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	17	-	ns
t_f	Fall Time	$V_{\text{GS}}=10\text{V}$	-	3.5	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	510	820	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	55	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	40	-	pF
R_g	Gate Resistance	f=1.0MHz	-	1.2	1.8	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_{\text{S}}=2.1\text{A}, V_{\text{GS}}=0\text{V}$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$I_{\text{S}}=4\text{A}, V_{\text{GS}}=0\text{V},$	-	27	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$	-	31	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t \leq 10sec ; 150 °C/W when mounted on Min. copper pad.
- 4.Starting $T_j=25^\circ\text{C}$, $V_{\text{DD}}=30\text{V}$, $L=0.1\text{mH}$, $R_G=25\Omega$.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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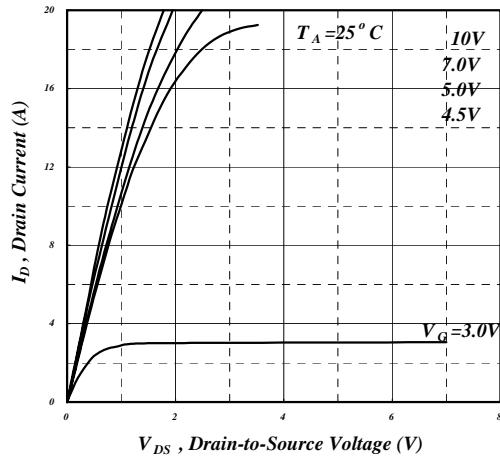


Fig 1. Typical Output Characteristics

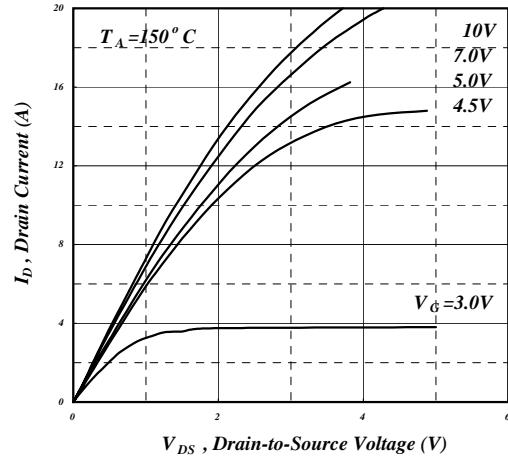


Fig 2. Typical Output Characteristics

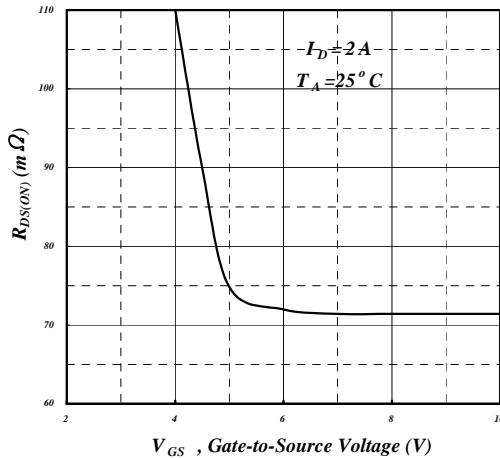


Fig 3. On-Resistance v.s. Gate Voltage

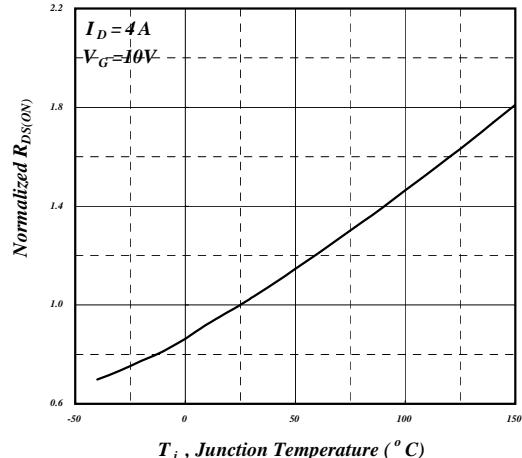


Fig 4. Normalized On-Resistance v.s. Junction Temperature

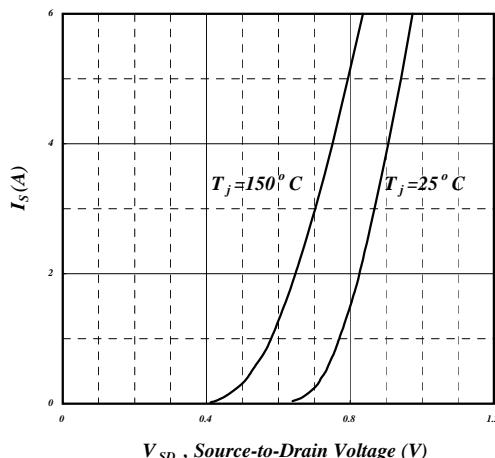


Fig 5. Forward Characteristic of Reverse Diode

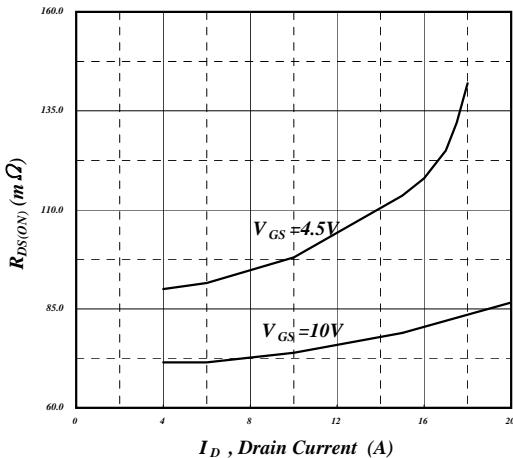


Fig 6. On-Resistance vs. Drain Current

AP9477GK-HF

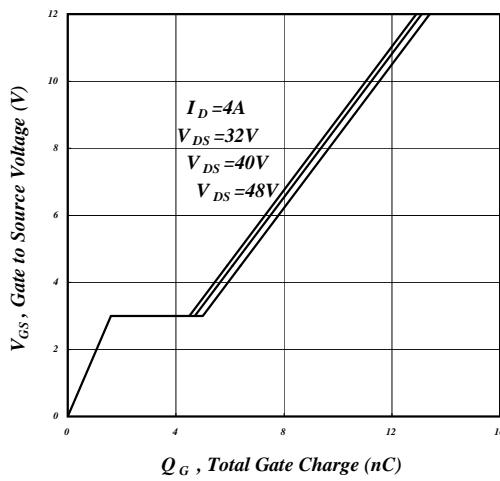


Fig 7. Gate Charge Characteristics

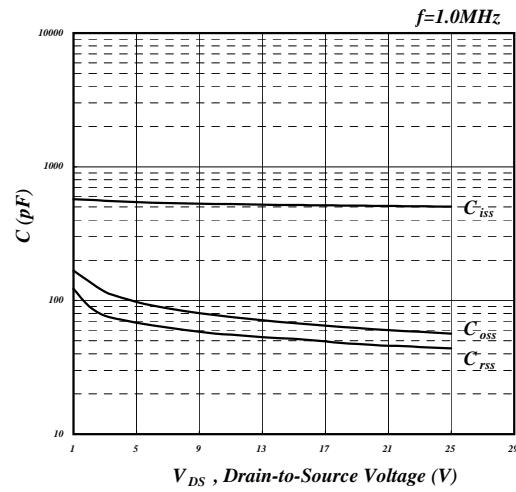


Fig 8. Typical Capacitance Characteristics

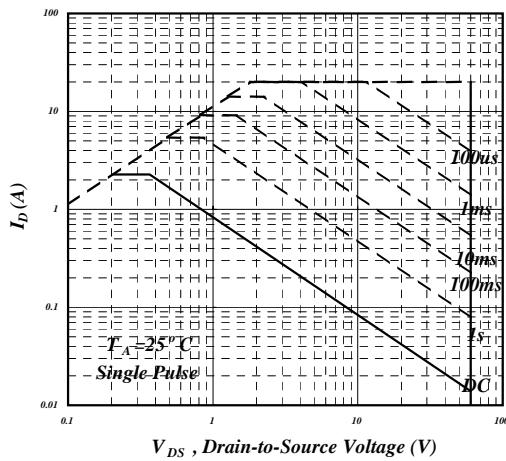


Fig 9. Maximum Safe Operating Area

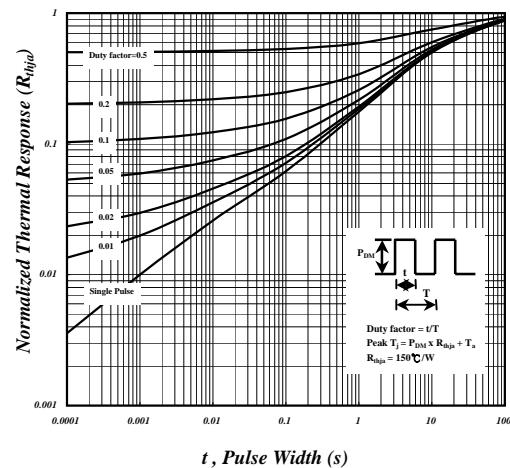


Fig 10. Effective Transient Thermal Impedance

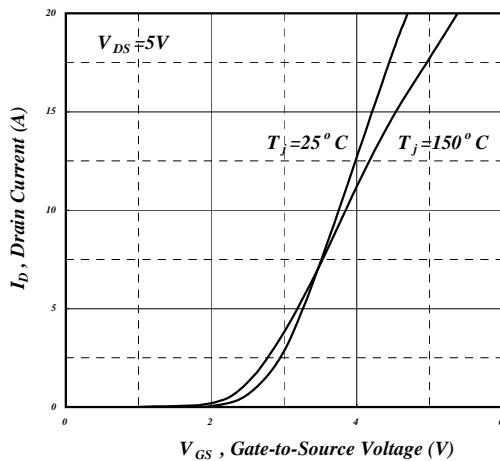


Fig 11. Transfer Characteristics

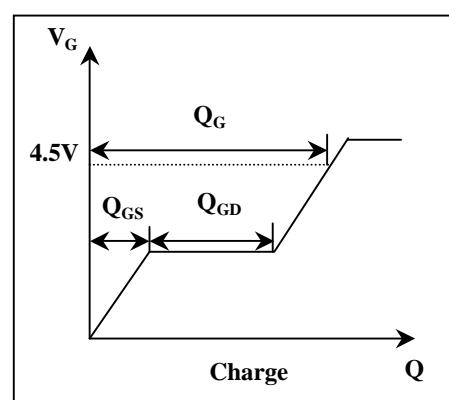


Fig 12. Gate Charge Waveform



MARKING INFORMATION

